

JPW



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Docket No: Q79041

Youichi KUKIMOTO et al

Conf. No.: 1863

Appln. No.: 10/765,931

Group Art Unit: 2823

Filed: January 29, 2004

Examiner: Nguyen, K.

For: SOLDER DISPOSITION METHOD AND
SOLDER BUMP FORMING METHOD

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is in response to the Office Action dated August 9, 2006, in the above-identified application, for which response is due on or before November 9, 2006.

The Patent Office is hereby directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Accordingly, please amend the above-identified application as follows.

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